

What is claimed is:

1. A contact pin used in an apparatus for testing characteristics of a semiconductor device, the contact pin comprising:
  - a barrel having a screw thread on an inside wall;
  - a contact tip formed at an end of the barrel;
  - a spring located inside the barrel and having an end connected to the contact tip;
  - a plunger formed at the other end of the barrel and connected to the other end of the spring; and
  - at least one screw moving together with the screw thread.
2. The contact pin of claim 1, wherein the at least one screw is connected to the plunger and the plunger rotates and moves up and down simultaneously.
3. The contact pin of claim 1, wherein the plunger has a tip electrically connected to a tester.
4. The contact pin of claim 1, wherein the contact tip is electrically connected to the semiconductor device through a probe card.
5. The contact pin of claim 1, wherein the contact tip is electrically connected to the semiconductor device through a socket board.
6. The contact pin of claim 1, wherein the contact tip is electrically connected to the semiconductor device through a connector.
7. The contact pin of claim 3, wherein a tip of the plunger is a crown type.
8. The contact pin of claim 3, wherein the tip of the plunger is a straight-line type.

9. The contact pin of claim 1, wherein the at least one screw is connected to the contact tip and the contact tip rotates and moves up and down simultaneously.

10. The contact pin of claim 9, wherein at least one screw is connected to the plunger and the plunger rotates and moves up and down simultaneously and at least one screw is connected to the contact tip and the contact tip rotates and moves up and down simultaneously.

11. A method for testing electrical characteristics of a semiconductor device, the method comprising:

providing a tester capable of performing an electrical test on the semiconductor device;

providing a connection unit, including at least one contact pin, for electrically connecting the semiconductor device and the tester;

electrically connecting the tester and the semiconductor device via a simultaneous rotating and up and down movement of the at least one contact pin; and

performing an electrical test on the semiconductor device.

12. The method of claim 11, wherein electrically connecting the semiconductor device and tester further includes connecting the contact tip to the semiconductor device through a probe card and connecting the plunger to the tester.

13. The method of claim 11, wherein electrically connecting the semiconductor device and the tester further includes connecting the contact tip to the semiconductor device through a socket board and connecting the plunger to the tester.

14. The method of claim 11, wherein electrically connecting the semiconductor device and the tester further includes connecting the contact tip to the semiconductor device through a connector and connecting the plunger to the tester.

15. The contact pin of claim 1, wherein said contact pin is a pogo pin.
16. The contact pin of claim 1, wherein said contact pin is part of a connection unit.
17. The contact pin of claim 1, wherein said contact pin is used in an apparatus for testing electrical characteristics of the semiconductor device.
18. A connection unit for testing characteristics of a semiconductor device, comprising:
- at least one contact pin including,
    - a barrel having a screw thread on an inside wall;
    - a contact tip formed at an end of the barrel,
    - a spring located inside the barrel and having an end connected to the contact tip,
    - a plunger formed at the other end of the barrel and connected to the other end of the spring; and
    - at least one screw moving together with the screw thread.
19. The connection unit of claim 18, wherein said contact pin is a pogo pin.
20. The connection unit of claim 18, wherein said contact pin is used in an apparatus for testing electrical characteristics of the semiconductor device.